



Material Content Data Sheet



Sales Product Name				IPP120N04S4-01		Issued		25. September 2017	
MA#				MA001055184					
Package				PG-TO220-3-1		Weight*		2037.61 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	6.481	0.32	0.32	3181	3181	
leadframe	non noble metal	iron	7439-89-6	0.816	0.04		401		
	inorganic material	phosphorus	7723-14-0	0.245	0.01		120		
	non noble metal	copper	7440-50-8	815.335	40.02	40.07	400142	400664	
wire	non noble metal	aluminium	7429-90-5	10.168	0.50	0.50	4990	4990	
encapsulation	organic material	carbon black	1333-86-4	8.820	0.43		4329		
	plastics	epoxy resin	-	97.020	4.76		47615		
	inorganic material	silicondioxide	60676-86-0	482.161	23.66	28.85	236631	288575	
leadfinish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10533	10533	
plating	non noble metal	nickel	7440-02-0	0.244	0.01		120		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	120	
solder	noble metal	silver	7440-22-4	0.115	0.01		57		
	non noble metal	tin	7440-31-5	0.092	0.00		45		
	non noble metal	lead	7439-92-1	4.411	0.22	0.23	2165	2267	
heatspreader	non noble metal	iron	7439-89-6	0.590	0.03		290		
	inorganic material	phosphorus	7723-14-0	0.177	0.01		87		
	non noble metal	copper	7440-50-8	589.466	28.93	28.97	289293	289670	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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